IN THE SPECIFICATION:

Please amend paragraph **[0005]** as follows:

[0005] Conventionally, the semiconductor industry favored a "final" electrical testing of semiconductor devices, which was effected before semiconductor devices were packaged with electrical leads extending therefrom and encapsulated in a protective material. However, it is now recognized that conventional packaging processes may ~~cause /significant~~ cause significant numbers of semiconductor devices to fail. For example, as a semiconductor device is being encapsulated, the protective material may cause particulate die coat penetration, "bond wire sweep," which may break electrical connections made by the bond wires or cause electrical shorts between adjacent bond wires, and other problems. Accordingly, it is desirable to test semiconductor devices after they have been packaged.

Please amend paragraph **[0069]** as follows:

[0069] Before initiation of a first layer for a support or object 50 is commenced, computer 12 automatically checks and, if necessary, adjusts by means known in the art, as referenced above, the surface level 18 of liquid material 16 in reservoir 14 to maintain same at an appropriate focal length for laser beam 28. Alternatively, the height of scan controller 24 may be adjusted responsive to a detected surface level 18 to cause the focal point of laser beam 28 to be located precisely at the surface of liquid material 16 at surface level 18 if level 18 is permitted to vary. The platform 20 may then be submerged in liquid material 16 in reservoir 14 to a depth greater than the thickness of one layer or slice 60 of the object 50 ~~(FIG. 10A),~~ (FIG. 10(F)), then raised to a depth equal to the thickness of a layer 60, and the liquid surface level 18 readjusted as required to accommodate liquid material 16 displaced by submergence of platform 20 while the surface of the material 16 in reservoir 14 settles to be free of ripples and other surface discontinuities which might result in an uneven layer when material 16 is subjected to laser beam 28. Laser 22 is then activated so that laser beam 28 will scan liquid material 16 over surface 30 of platform 20 to at least partially cure (e.g., at least partially polymerize) liquid material 16 at selected locations, defining the boundaries of a first layer 60 (of object 50 or a

support therefor, as the case may be) and filling in solid portions thereof. Platform 20 is then lowered by a distance greater than the thickness of a layer 60, raised to a depth equal to the thickness thereof, and the laser beam 28 scanned again to define and fill in the second layer 60 while simultaneously bonding the second layer to the first. The process is then repeated, layer by layer, until object 50 is completed.

Please amend paragraph **[0071]** as follows:

[0071] Each layer 60 of object 50 is preferably built by first defining any internal and external object boundaries of that layer 60 with laser beam 28, then hatching solid areas of object 50 with laser beam 28. The internal and external object boundaries of all layers 60 comprise an envelope 80 whose boundaries are set by the software (see ~~FIGS. 10B-10E).~~ FIGs. 10(B)-10(E)). If a particular part of a particular layer 60 is to form a boundary of a void in the object above or below that layer 60, then the laser beam 28 is scanned in a series of closely spaced, parallel vectors so as to develop a continuous surface, or skin, with improved strength and resolution. The time it takes to form each layer 60 depends upon its geometry, surface tension and viscosity of material 16, and thickness of the layer.

Please amend paragraph **[0091]** as follows:

[0091] Although stereolithography is a preferred method for forming an interposer 100 of the invention, having many advantages described above, known molding processes may nonetheless be used to fabricate fence 120 of interposer 100. FIG. 11 schematically illustrates an exemplary mold 170 in which an interposer substrate 110 may be positioned to form a fence 120, 120', 120", 120"' (see FIGs. 1, 1A, 2, 3, 6-8) thereon. As illustrated, mold 170 has an upper mold half 172 and a lower mold half 174. Upper mold half 172 is shown with receptacles 184 for receiving any protecting, projecting portions of contact pads 102. Lower mold half 174 is shown with upwardly extending projections 186 which form apertures through the lower protective layer of fence 120, through which contact pads 106 will be exposed. In addition, when biased against an interposer substrate 110, projections 186 prevent leakage of mold material onto contact pads 102, 106, as well as damage that may be caused to interposer substrate 110 as mold material is introduced into cavity 180.